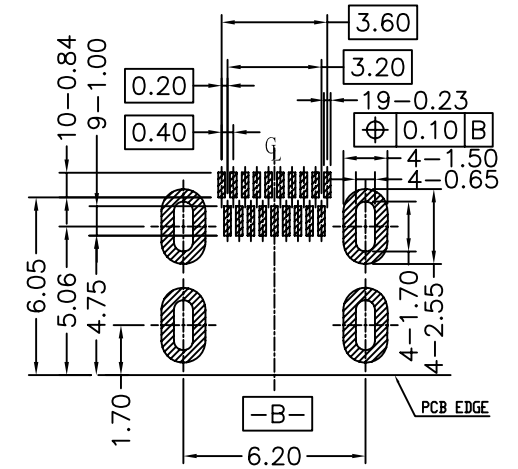


PART NO:
HHF-12X001-XSD

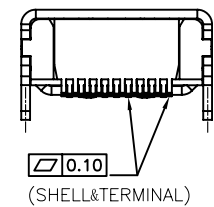
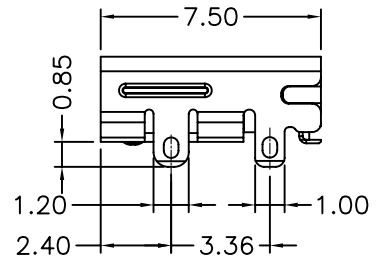
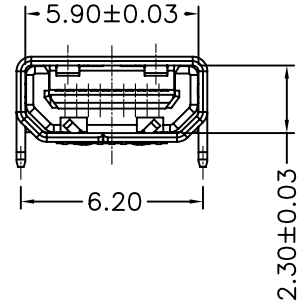
PACKAGING CODE
1: TARY PACKING
2: TAPE REEL PACKAGEING
3: TUBE PACKING

TERMINAL CONTACT AREA PLATING CODE:
1: CONTACT AREA: GOLD FLASH
SOLDER AREA: GOLD FLASH
2: CONTACT AREA: 3u" GOLD
SOLDER AREA: GOLD FLASH
A: CONTACT AREA: GOLD FLASH
SOLDER AREA: MATTE TIN 100u"
B: CONTACT AREA: 3u" GOLD
SOLDER AREA: MATTE TIN 100u"

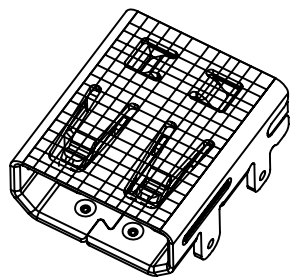
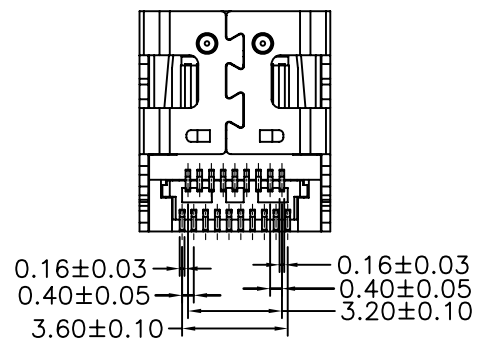
MYLAR:
0: WITHOUT MYLAR
1: WITH MYLAR



RECOMMENDED PCB LAYOUT(.XX±0.05)
CONNECTOR SIDE(TOP VIEW)



NOTE:
1.MATERIAL AND FINISH SEE THE TABLE.
2.MECHANICAL CHARACTERISTICS
INSERTION FORCE: 44.1N MAX
EXTROCTION FORCE: 5N MIN(AFTER 5000 CYCLES
3N MIN.), 25N MAX.
MATING CYCLE:5000 CYCLES
3.ELECTRICAL CHARACTERISTICS
RATING CURRENT: 0.5A
RATING VOLTAGE: 40V
CONTACT RESISTANCE: 10 MILLOHMS OHMS MAX
(EXCLDUING CONDUCTOR RESISTANCE)
INSULATION RESISTANCE:
a, UNMATED: 100M OHMS MIN AT 500 VDC
b, MATED: 10M OHMS MIN AT 150 VDC
DIELECTRIC WITHSTANDING VOLTAGE:
250V AC/1MINUTE
OPERATING TEMPERATURE: -20°C--+85°C
STORAGE TEMPERATURE: -20°C--+65°C
4.MARKED ⊗ DIMENSION SHOULD BE MEASURED BY QIP;



MATERIAL	TOLERANCE UNSPECIFIED	ZheJiang HeFeng Technology Co.,Ltd	SCALE	UNIT	
	0.0 ±0.30		0° ±2°	1:1	mm
	0.00 ±0.20		.0° ±1°		
	0.000 ±0.10		.0° ±0.5°		
FINISH	DRAWN	NAME HDMI D/F TYPE SMT TYPE SHELL LEG DIP+DIP (HSD-1 Series)	SHEET		
	Chu		11/03/02	1/1	
	DESIGNER				
	Chu		11/03/02		
	CHECKED				
	APPROVED	DRAWING NO.	REV		
		HHF-1XX001-XSD	A		

A	新版发行	chu	2012-03-13
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期